

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUS300N08S5N012	**Issued**	16. May 2021
MA#	MA005344603		
Package	PG-HSOG-8-1	**Weight***	708.54 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.727	1.09	1.09	10906	10906
leadframe	inorganic material	phosphorus	7723-14-0	0.040	0.01		57	
	non noble metal	iron	7439-89-6	0.134	0.02		190	
	non noble metal	copper	7440-50-8	134.219	18.94	18.97	189430	189677
wire	non noble metal	aluminium	7429-90-5	18.670	2.64	2.64	26350	26350
encapsulation	inorganic material	zincoxide	1314-13-2	2.569	0.36		3626	
	miscellaneous	miscellaneous	-	10.276	1.45		14503	
	plastics	epoxy resin	-	38.535	5.44		54387	
	inorganic material	silicondioxide	60676-86-0	205.521	29.01	36.26	290062	362578
leadfinish	non noble metal	tin	7440-31-5	8.309	1.17	1.17	11727	11727
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.220	0.03	0.03	310	311
solder	non noble metal	tin	7440-31-5	0.125	0.02		177	
	noble metal	silver	7440-22-4	0.156	0.02		221	
	non noble metal	lead	7439-92-1	5.973	0.84	0.88	8430	8828
heatspreader	inorganic material	phosphorus	7723-14-0	0.083	0.01		117	
	non noble metal	iron	7439-89-6	0.276	0.04		390	
	non noble metal	copper	7440-50-8	275.705	38.91	38.96	389116	389623
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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